

**SEMICONDUCTOR PACKAGES AND METHODS FOR MAKING THE SAME****Abstract of the Invention**

Semiconductor package support elements including cover members

5 attached to one or more reject die sites are provided. Methods for making the support elements of the present invention and for making semiconductor packages using the same are also provided. Reject die sites on defective substrates of a support element are covered prior to the encapsulation process using a cover member. The cover member comprises, for example, pressure-sensitive or temperature-activated tape, reject dies, or the like. The support elements and methods of the present invention virtually eliminate bleeding or flashing during encapsulation due to the presence of reject die sites. The support elements and methods of the present invention further ensure that functional dice are not sacrificed by being attached to reject die sites, thereby 10 decreasing manufacturing costs while increasing yield of functional 15 semiconductor packages.